

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

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[**] Term: 14 Years

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[58] Field of Search D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

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[57] CLAIM

The ornamental design for a heat releasing plate for mounting semiconductor components, as shown and described.

DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semiconductor components showing the new design;

FIG. 2 is a plan view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a bottom view thereof;

FIG. 5 is a right side view thereof; and

FIG. 6 is a sectional view taken on line 6—6 of FIG. 1.

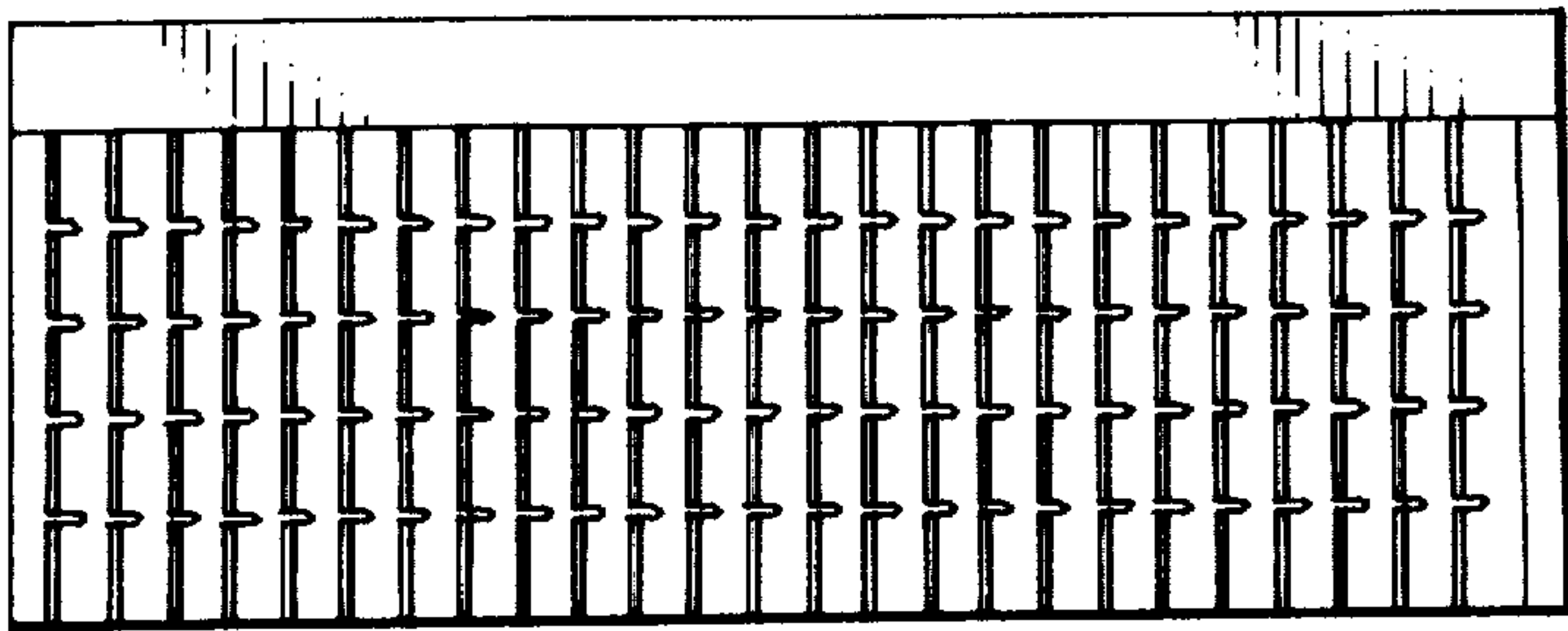
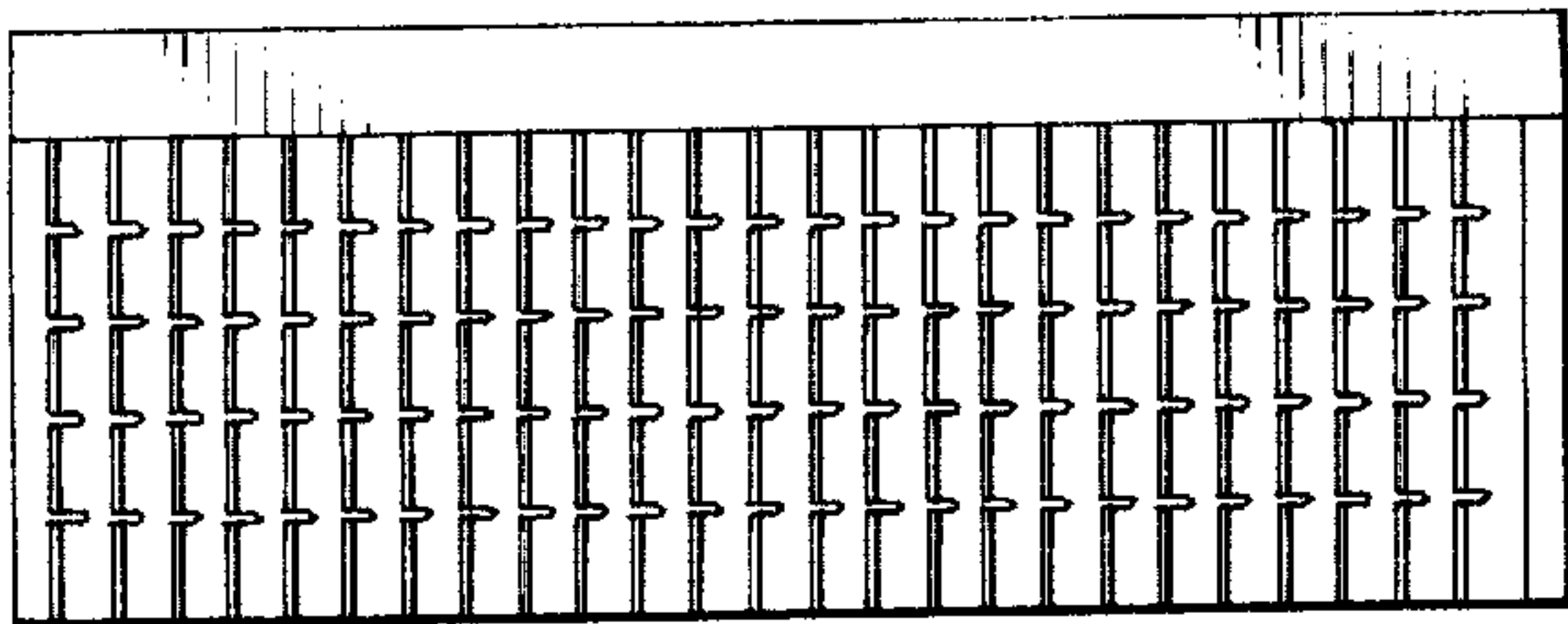
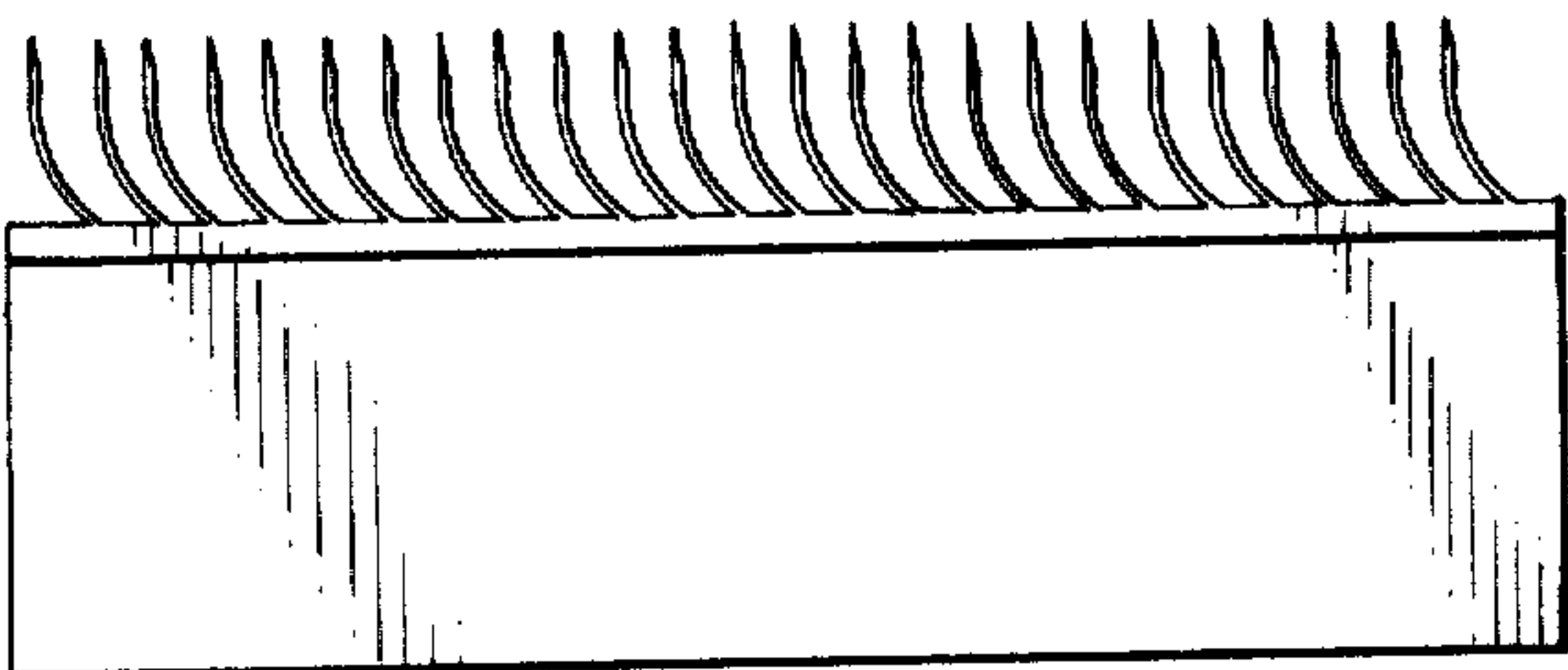


FIG. 2 .



6 — FIG. 1 .



6 — FIG. 4 .

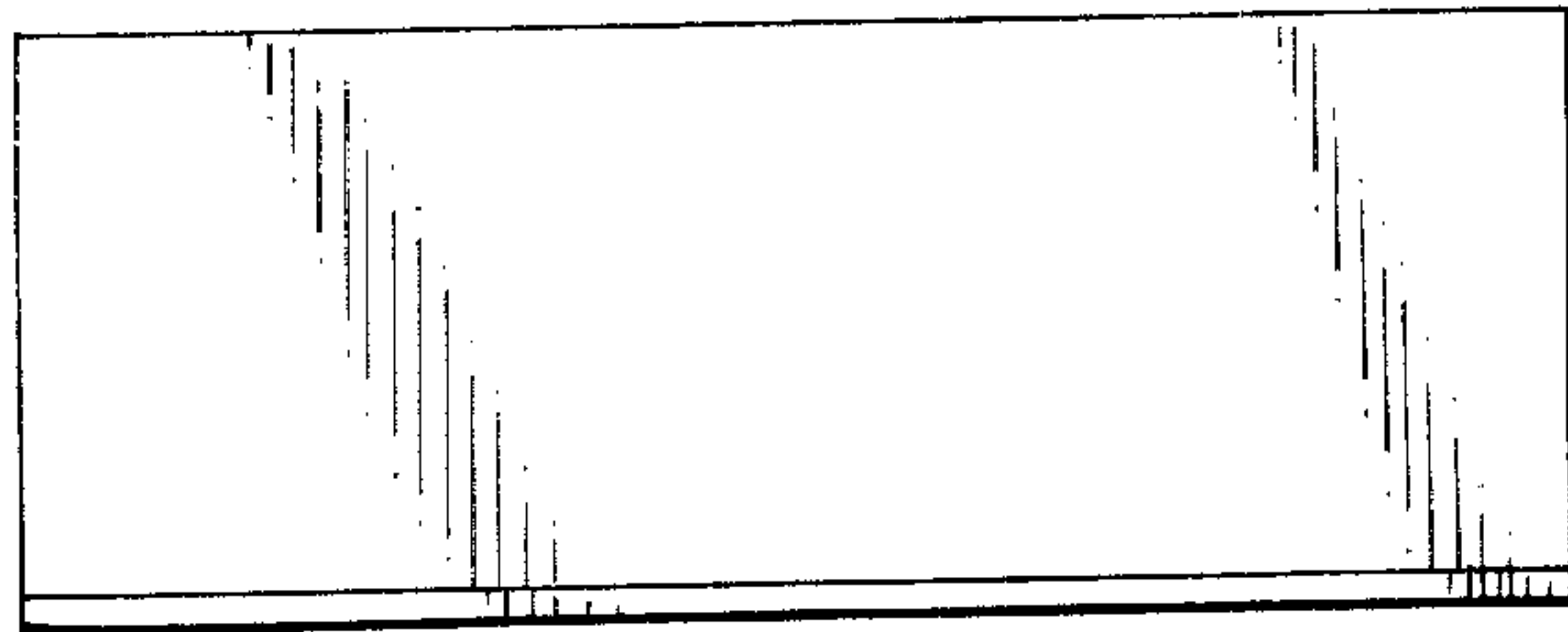


FIG. 3 .

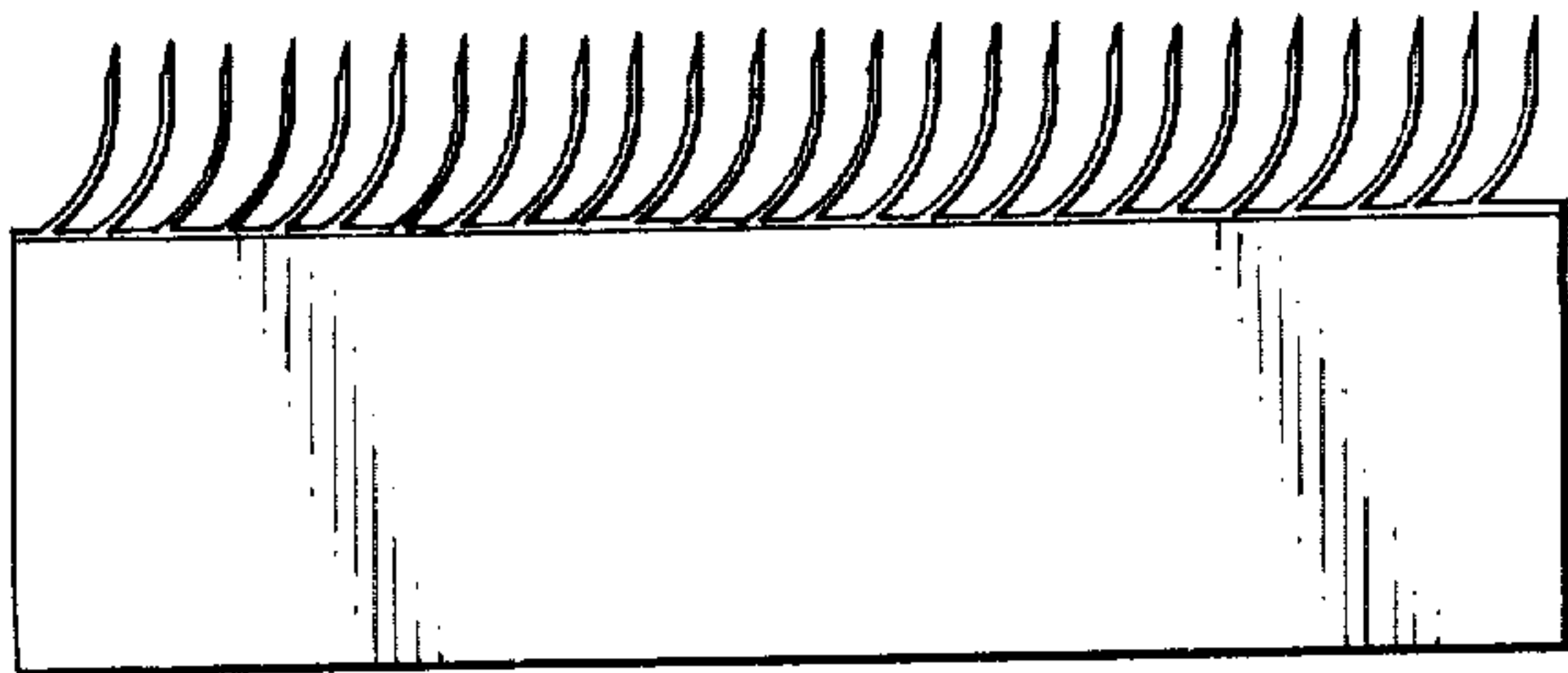


FIG. 5 .

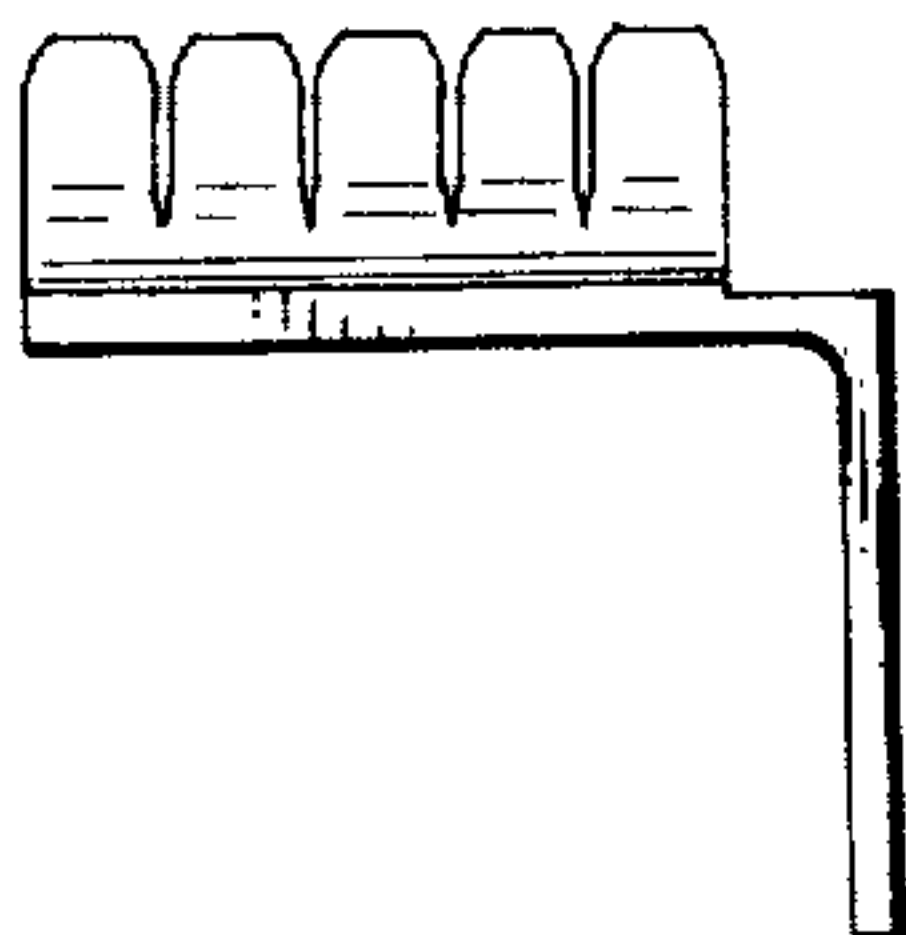


FIG. 6 .

